



## Material Content Data Sheet



<b>Sales Product Name</b>		BSO040N03MS G		<b>Issued</b>		25. September 2017		
<b>MA#</b>		MA000468338						
<b>Package</b>		PG-DSO-8-39		<b>Weight*</b>		83.82 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.840	2.20	2.20	21954	21954
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		122	
	non noble metal	zinc	7440-66-6	0.041	0.05		489	
	non noble metal	iron	7439-89-6	0.820	0.98		9777	
wire	non noble metal	copper	7440-50-8	33.276	39.70	40.74	397006	407394
	non noble metal	copper	7440-50-8	0.374	0.45	0.45	4462	4462
	encapsulation	organic material	carbon black	1333-86-4	0.230	0.27		2742
plastics		epoxy resin	-	7.124	8.50		84997	
	inorganic material	silicondioxide	60676-86-0	38.609	46.05	54.82	460629	548368
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9710	9710
plating	noble metal	silver	7440-22-4	0.073	0.09	0.09	866	866
glue	plastics	epoxy resin	-	0.091	0.11		1087	
	noble metal	silver	7440-22-4	0.516	0.62	0.73	6159	7246
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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